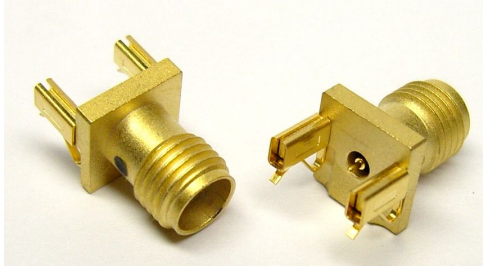


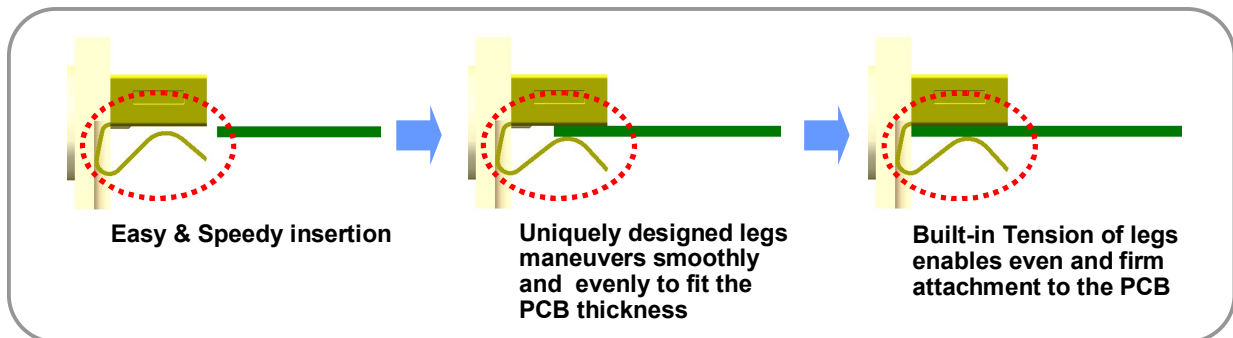
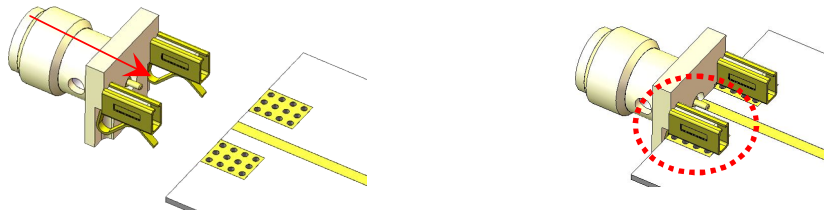
Quick End Launch (QEL™ SMA)



GigaLane's **Quick End Launch (QEL™ SMA)** is designed for quick launch at the edge of PCB board up to 18 GHz. Our specially designed leg immediately adjusts and firmly holds its attachment with the PCB. It is ideal solution for all active & speedy tests required in R&D. When compared with conventional end launch connector, it will effectually reduce soldering and assembly time when deployed in mass production.



- ✓ Quick Launch for active and speedy results
- ✓ DC to 18 GHz
- ✓ Easy & Free fixation for various PCB thickness
- ✓ Effectiveness in mass production
- ✓ Eco-friendly & 'GREEN' product: less soldering



■ Specification

Electrical Data	Impedance	50 Ohm
	Max. Freq.	18 GHz
	VSWR	1.25 Max up to 18 GHz
	Insulation Resistance	Min. 5 Giga Ohms
Mechanical Data	Force to Engage/Disengage	2.0 pounds max.
	Durability	500 mating cycles
	Recommended Mating Torque	7~10 inch-pounds
Environmental Data	Operating Temp.	-40°C~125°C
	Vibration	MIL-STD-202
	Shock	MIL-STD-202
	RoHS	Compliant

Where **Signal and Connectivity** is needed,
There is GigaLane

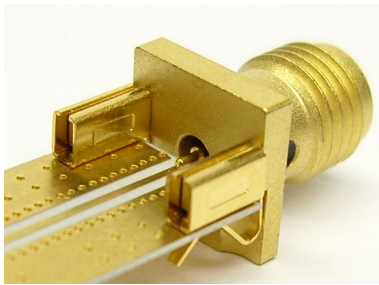
www.gigalane.com
sales@gigalane.com

Part number & Board clearance

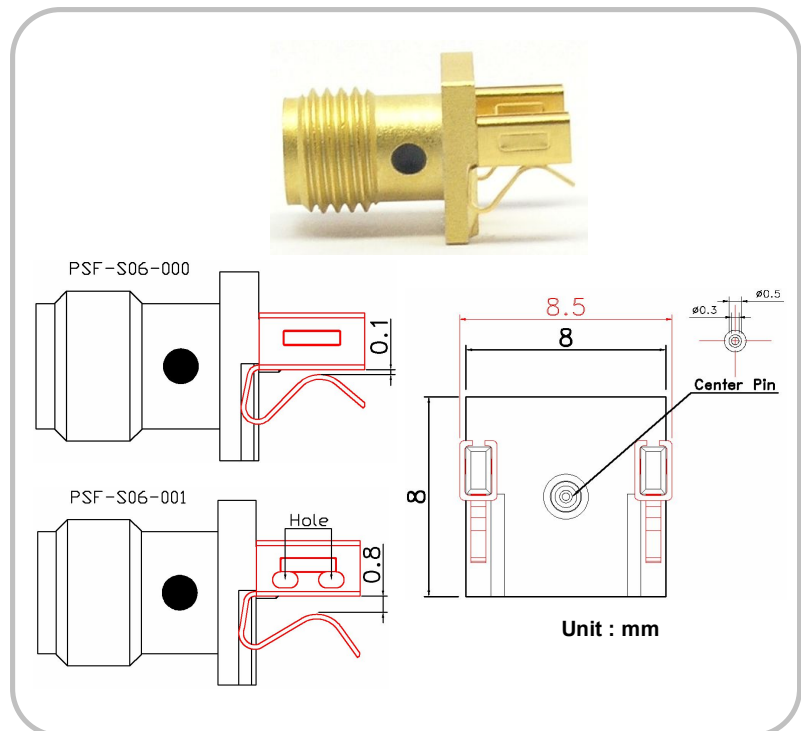
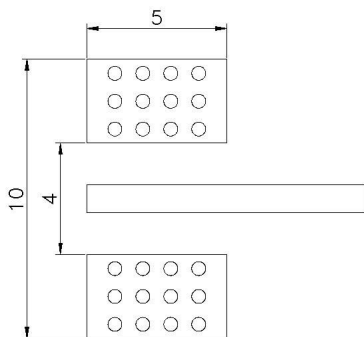
Part No.	Board Clearance
PSF-S06-000	0.25 ~ 1.2 mm
PSF-S06-001	1.25 ~ 2.0 mm

※ As described in the table, 2 product specifications are available to accordingly cover all common PCB thicknesses.

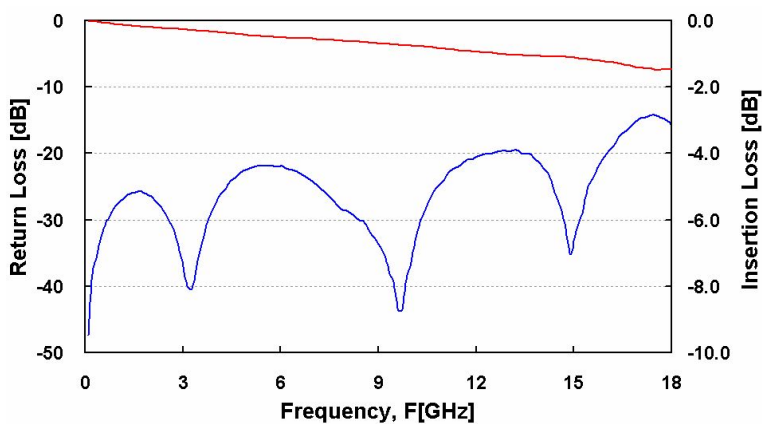
Drawing & PCB pattern



RECOMMENDED PCB MOUNT



Performance



<DUT>

Connector

- PSF-S06-000: 2ea

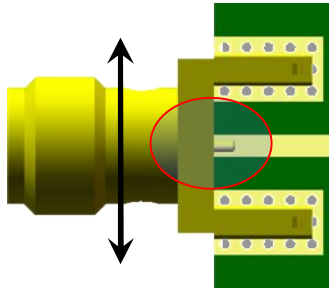
PCB

- FR4 Sub Thickness : 0.6 mm

- 50 Ω Line Width : 1.2 mm

- Line Length : 18 mm

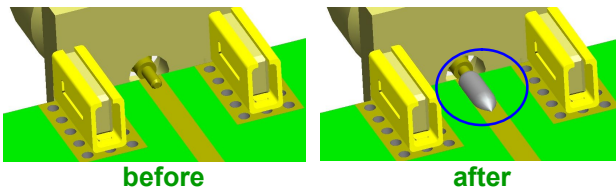
■ Soldering Guide



QEL Connector must be launched on the center of PCB while moving such as arrow direction.

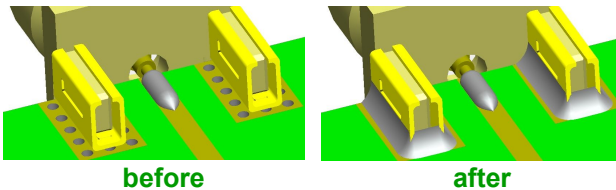
■ Soldering Flow & Notice

1. Center Conductor Soldering

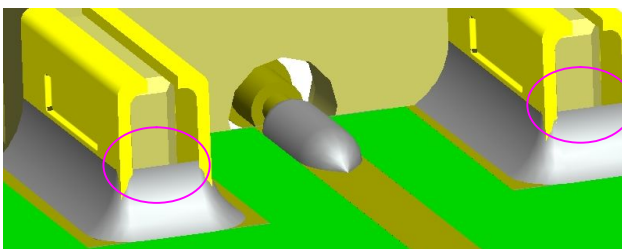


1. When center pin soldering, must not be soldered to internal QEL SMA.
2. Must be soldered to internal QEL SMA Clip.
3. When soldering, Signal & GND must be separated.

2. Top Ground Plate Soldering



4. Must be careful Cold Soldering.



3. Bottom Ground Plate Soldering

